

2SA1171

Silicon PNP Epitaxial

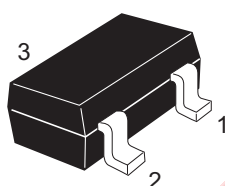
REJ03G0638-0200
(Previous ADE-208-1010)
Rev.2.00
Aug.10.2005

Application

Low frequency small signal amplifier

Outline

RENESAS Package code: PLSP0003ZB-A
(Package name: MPAK)



- 1. Emitter
- 2. Base
- 3. Collector

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-90	V
Collector to emitter voltage	V_{CEO}	-90	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_C	-50	mA
Collector power dissipation	P_C	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-90	—	—	V	$I_C = -1 \text{ mA}$, $R_{BE} = \infty$
Collector cutoff current	I_{CBO}	—	—	-0.5	μA	$V_{CB} = -75 \text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE}^{*1}	250	—	800		$V_{CE} = -12 \text{ V}$, $I_C = -2 \text{ mA}$
Base to emitter voltage	V_{BE}	—	—	-0.75	V	$V_{CE} = -12 \text{ V}$, $I_C = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	-0.5	V	$I_C = -10 \text{ mA}$, $I_B = -1 \text{ mA}$
Gain bandwidth product	f_T	—	200	—	MHz	$V_{CE} = -12 \text{ V}$, $I_C = -2 \text{ mA}$
Collector output capacitance	C_{ob}	—	1.6	—	pF	$V_{CB} = -25 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$

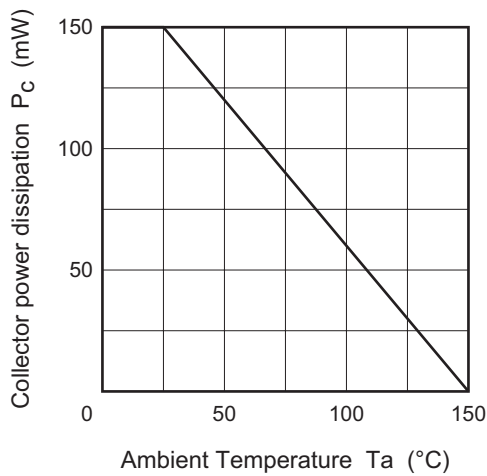
Note: 1. The 2SA1171 is grouped by h_{FE} as follows.

Grade	D	E
Mark	PD	PE
h_{FE}	250 to 500	400 to 800

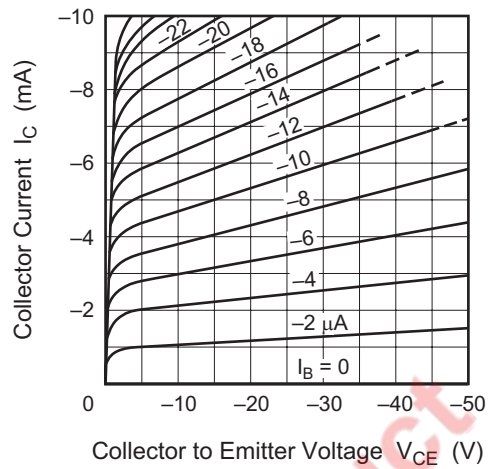
EOL announced Product

Main Characteristics

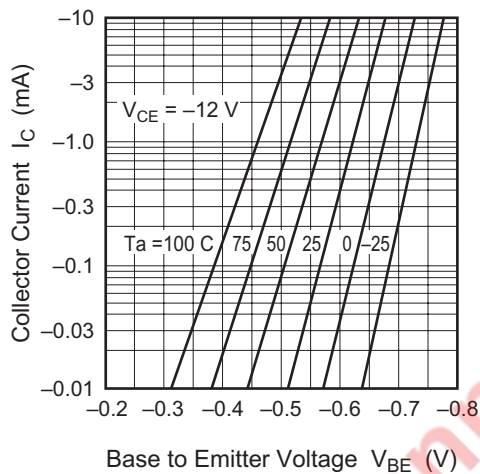
Maximum Collector Dissipation Curve



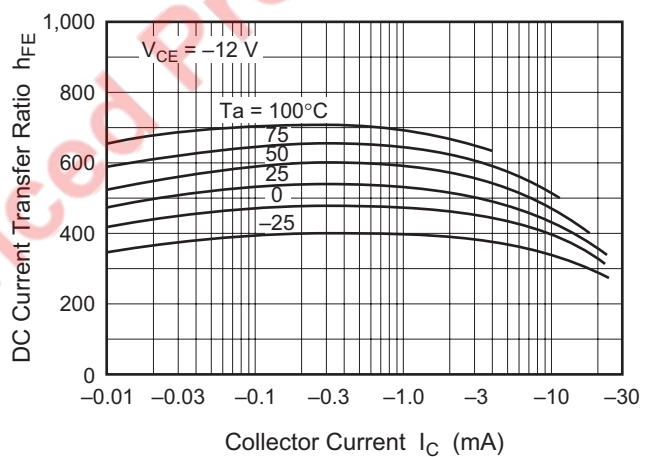
Typical Output Characteristics



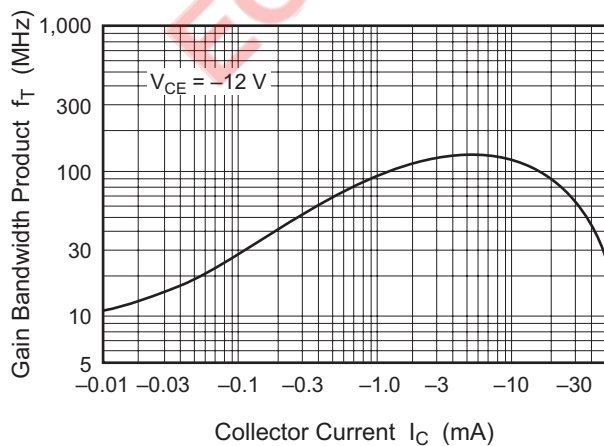
Typical Transfer Characteristics



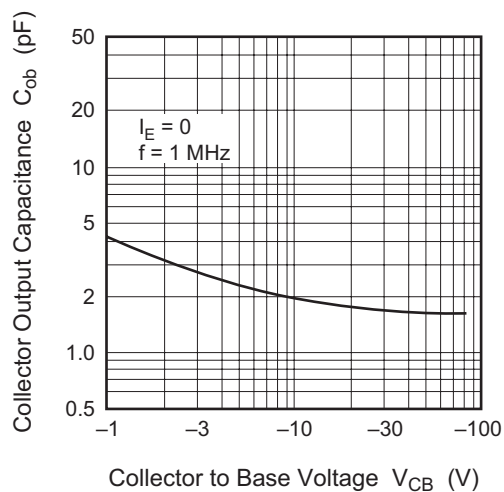
DC Current Transfer Ratio vs. Collector Current



Gain Bandwidth Product vs. Collector Current



Collector Output Capacitance vs. Collector to Base Voltage



Package Dimensions

JEITA Package Code	RENESESAS Code	Package Name	MASS[Typ.]
SC-59A	PLSP0003ZB-A	MPAK(T) / MPAK(T)/V, MPAK / MPAKV	0.011g

A-A Section

Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	1.0	—	1.3
A ₁	0	—	0.1
A ₂	1.0	1.1	1.2
A ₃	—	0.25	—
b	0.35	0.42	0.5
b ₁	—	0.4	—
c	0.1	0.13	0.15
c ₁	—	0.11	—
D	2.7	—	3.1
E	1.35	1.5	1.65
e	—	0.95	—
HE	2.2	2.8	3.0
L	0.35	—	0.75
L ₁	0.15	—	0.55
L _P	0.25	—	0.65
x	—	—	0.05
b ₂	—	—	0.55
e ₁	—	1.95	—
l ₁	—	—	1.05
Q	—	0.3	—

Ordering Information

Part Name	Quantity	Shipping Container
2SA1171PDTR-E 2SA1171PETR-E	3000	φ 178 mm Reel, 8 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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